© Copyright 20	<b>mposition De</b> 05. IPC, Bannock d Pan-American c	burn, Illinois. A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declarati he declaration e	on of the su	ibstances v s all lower	within the manufactu level materials for w	rer listed ite hich the ma	m. Note: i nufacturer	f the item is an as has engineering	sembly with low responsibility.
	IPC Web Site for Information on IPC-1752 Standard Form Typ   http://www.ipc.org/IPC-175x Distribute			*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials a					s and Mfg Information			
Supplier Information													
Company name* Compan			mpany unique ID			Unique ID Authority				Response Date*			
onsemi										2024-05-18			
Contact Name Title - Conta			atact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product			duct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Repr			epresentative			Phone - Representative*				Email - Representative*			
Product-Env-Stewards Product			roduct Enviro Compliance			NA				Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Iter	n Number	Mfr Item Name			Effective Date	Version	М	Ianufacturing Site	W	'eight*	UOM	Unit Type
	NTMJS WG			T6 60V LL LFPAK		2024-05-18		PI	PBB		9.445	mg	Each
Aanufacturing Proccess Info	mation												
Terminal Plating / Grid Arra	ninal Plating / Grid Array Material Terminal Base .		Alloy	J-STD-020 MSL Rating		Peak Process Body Temperature Max Tim		e Max Time at Peak	eak Temperature Number of Reflow Cycles		les		
Matte Tin (Sn) - annealed CU		CU Alloy	Alloy 1			<b>260</b> C		С	30 seco		seconds 3		
omments													
vel 1 - maximum time at peak temp	erature during so	oldering is 10-3	0 seconds										
or more information regarding mat	erial composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed					
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).									
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, admium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part ontains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall ncompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledge and belief, so of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the ROHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not ndependently verified information provided by others, Supplier agrees that, at a minimum, itsuppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the ertification in this paragraph. If the Company and the Supplier remedies of issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the varrant										
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted					
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).							
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the					
Supplier Digital Signature	astislav Drska	Le								

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	6.9	mg	Supplier	Iron (Fe)	7439-89-6		0.0083	mg
			Supplier	Copper (Cu)	7440-50-8		6.8896	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0021	mg
Die	1.1	mg	Supplier	Silicon (Si)	7440-21-3		1.1	mg
Lead Frame	36.7	mg	Supplier	Silver (Ag)	7440-22-4		0.0037	mg
			Supplier	Iron (Fe)	7439-89-6		0.044	mg
			Supplier	Copper (Cu)	7440-50-8		36.6413	mg
			Supplier	Phosphorus (P)	7723-14-0		0.011	mg
Mold Compound-Black	41.4	mg	Supplier	Trimethoxysilylpropanethiol	4420-74-0		0.207	mg
			Supplier	Boron zinc hydroxide oxide	138265-88-0		6.21	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		6.21	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1035	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		26.3925	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.277	mg
lating	6.3	mg	Supplier	Tin (Sn)	7440-31-5		6.3	mg
Solder Paste	7.0	mg	Supplier	Silver (Ag)	7440-22-4		0.175	mg
			А	Lead (Pb)	7439-92-1	7a	6.475	mg
			Supplier	Tin (Sn)	7440-31-5		0.35	mg
Wire Bond - Cu	0.045	mg	Supplier	Copper (Cu)	7440-50-8		0.045	mg